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Abstract

Insulation material for aluminum and copper metalizations

The invention relates to a dielectric for aluminum and copper metalizations which is stable at high temperatures. Surprisingly - in spite of the elimination of water during the cyclization - the polymeric dielectrics are very suitable for filling narrow trenches. The filled trenches exhibit no defects and bubbles or cracks at all. The polybenzoxazoles have dielectric constants of $k \leq 2.7$ and are suitable as an electrical insulator. Furthermore, these materials adhere very well on all surfaces relevant for micro-electronics.

Fig. 1